

Environmental influence on the surface chemistry of ionic-liquid-mediated lubrication in a silica / silicon tribopair

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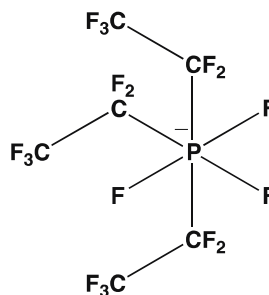
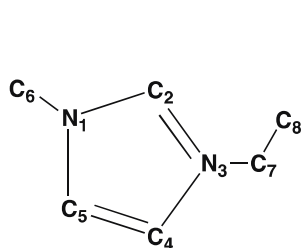
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The **peak-fitting** parameters for the high-resolution XP-spectra of tribostressed samples are reported in Tables S1-S2. A list of the binding energies of the compounds considered for the chemical-state analysis of the tribostressed wafer is reported in Table S3. Three replicas of a tribological test carried out in the presence of humid air with [HMIM] FAP as a lubricant, applying a load of 0.5 N are reported in Figure S1. Replicas of the tribological tests carried out applying a load of 4.5 N are reported in Figure S2, S3, S4, and S5. The survey and high-resolution spectra of tribostressed silicon disks lubricated with [EMIM] FAP, applying a load of 4.5 N, are reported in Figures S6-S8. Optical and scanning electron micrographs of tribostressed disks lubricated with [EMIM] FAP are reported in Figures S9 and S10.

Ionic Liquids used in the present study:

[EMIM]
FAP



[HMIM]
FAP

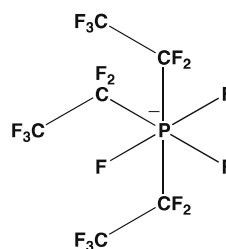
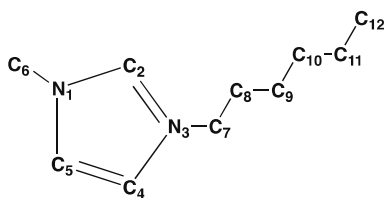


Table S1: Peak-fitting parameters for the XP-spectra of silicon samples tribostressed with [EMIM] FAP or [HMIM] FAP ionic liquids in the presence of a nitrogen atmosphere. Normal load: 4.5 N, sliding speed: 50 mm/min, number of cycles: 200, radius: 3.2 mm. The uncertainty in the binding energies (BE) and in the full widths at half-maximum (FWHM) is 0.2 eV.

		<i>Line shape</i>	<i>Contact area</i>		<i>Non-contact area</i>	
			<i>BE (eV)</i>	<i>FWHM (eV)</i>	<i>BE (eV)</i>	<i>FWHM (eV)</i>
C1s*	SiC_xO_y	GL(30)	283.8	1.4	-	-
	$C-C$	GL(30)	285.0	1.4	285.0	1.4
	$C-O$	GL(30)	286.3	1.4	286.3	1.4
	$C=O$	GL(30)	287.6	1.4	286.6	1.4
N1s	SiN_xO_y	GL(30)	398.2	1.8	-	-
F1s	$F-Si$	GL(30)	686.8	1.8	-	-
	SiO_xF_y	GL(30)	687.9	1.8	687.9	1.7
O1s	$O-Si$	GL(50)	532.9	1.9	533.1	1.7
Si2p _{3/2} **	Si^0	LA(1.5,1.8,65)	99.3	0.6	99.3	0.6
	Si^+	GL(30)	100.3	0.9	100.3	0.9
	Si^{2+}	GL(30)	101.2	0.9	101.2	0.9
	Si^{3+}	GL(30)	101.8	0.9	101.8	0.9
	Si^{4+}	GL(30)	103.2	1.8	103.6	1.5

*The position of the C-O and COOX components are constrained at a distance of +1.3 and +1.6 eV from the C-C signal. The FWHM of the C1s components is constrained at 1.4 eV.

** The position of the components having intermediate oxidation states are constrained according to Seah et al. ¹

Table S2: Peak-fitting parameters for the XP-spectra of silicon samples tribostressed with [EMIM] FAP or [HMIM] FAP ionic liquids in the presence of a humid air (45% - 55% RH). Normal load: 4.5 N, sliding speed: 50 mm/min, number of cycles: 200, radius: 3.2 mm. The uncertainty of the binding energies (BE) and of the full widths at half-maximum (FWHM) is 0.2 eV.

		<i>Line shape</i>	<i>Contact area</i>		<i>Non contact area</i>	
			<i>BE (eV)</i>	<i>FWHM (eV)</i>	<i>BE (eV)</i>	<i>FWHM (eV)</i>
C1s	SiC_xO_y	GL(30)	284.0	1.4	-	-
	$C-C$	GL(30)	285.0	1.4	285.0	1.4
	$C-O$	GL(30)	286.3	1.4	286.3	1.4
	$C=O$	GL(30)	287.6	1.4	286.6	1.4
N1s	SiN_xO_y	GL(30)	-	-	-	-
F1s	$F-Si$	GL(30)	686.8	1.8	-	-
	SiO_xF_y	GL(30)	687.9	1.8	687.9	1.8
O1s	$O-Si$	GL(50)	533.1	2.0	533.1	1.7
Si2p _{3/2}	Si^0	LA(1.5,1.8,65)	93.0	0.6	93.0	0.6
	Si^+	GL(30)	100.3	0.9	100.3	0.9
	Si^{2+}	GL(30)	101.2	0.9	101.2	0.9
	Si^{3+}	GL(30)	101.8	0.9	101.8	0.9
	Si^{4+}	GL(30)	103.6	1.8	103.6	1.5

*The positions of the C-O and COOX components are constrained at a distance of +1.3 and +1.6 eV from the C-C signal. The FWHM of the C1s components is constrained at 1.4 eV.

** The position of the components having intermediate oxidation states is constrained according to Seah et al. ¹

Table S3: Binding energies of the compounds considered for the chemical-state analysis of the tribostressed silicon disks.

	<i>Chemical state</i>	<i>Binding energy (eV)</i>
Si2p	Silicon ²	99.3
	Silicon carbide ³	100.2
	Silicon oxycarbide ³	100.6-101.4
	SiO _x (Si ⁺¹) ¹	100.3
	SiO _x (Si ⁺²) ¹	101.2
	SiO _x (Si ⁺³) ¹	101.8
	SiO _x (Si ⁺⁴) ¹	102.6 – 104.1
	Si-F (Si ⁺¹) ⁴	100.3 – 100.5
	S-F (Si ⁺²) ⁴	101.3 – 100.8
	Si-F (Si ⁺³) ⁴	102.4 – 102.8
C1s	Silicon carbide ⁵	283.0
	Silicon oxycarbide ³	283.6
	Graphitic ⁶	284.4
	Organic bonded to Si ⁷	283.9
	Aliphatic ⁸	285.0
	Carbon bound to oxygen ⁸	286.1-286.6
		287.8
N1s	Silicon oxynitride ⁹	398.3
F1s	Silicon oxyfluoride ¹⁰	686.4
	Si-F ¹⁰	687.8 – 688.0

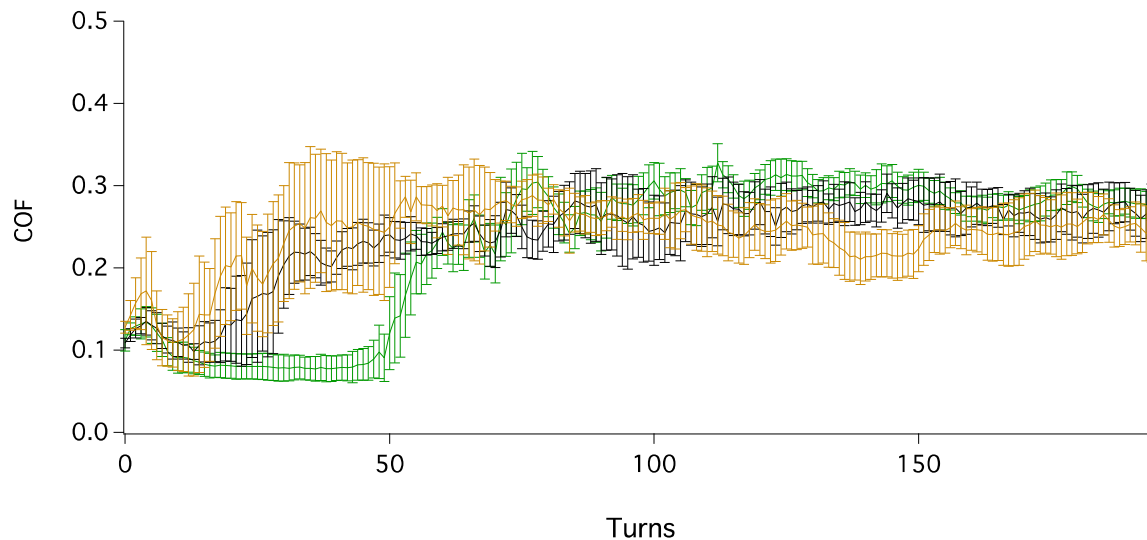


Figure S1: Coefficient of friction versus number of cycles (sliding time) during three tribological tests (normal load: 0.5 N sliding speed: 50 mm/min, radius: 3.2 mm) carried out in the presence of [HMIM] FAP at room temperature (296 ± 2 K) and humid air (45% - 55% RH). Error bars express the standard deviation of friction data over a single cycle.

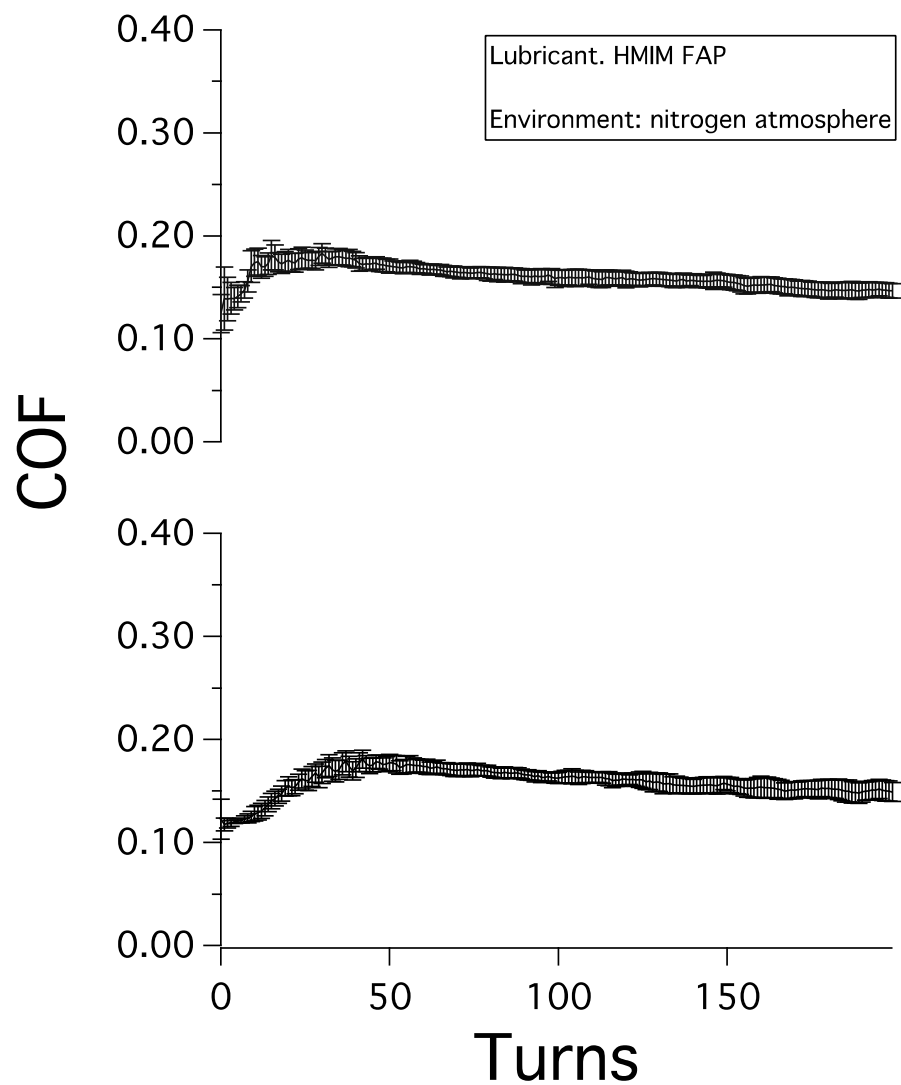


Figure S2: Coefficient of friction versus number of cycles (sliding time) during two tribological tests (normal load: 0.5 N sliding speed: 50 mm/min, radius: 3.2 mm) carried out in the presence of [HMIM] FAP at room temperature (296 ± 2 K) and under nitrogen. Error bars express the standard deviation of friction data over a single cycle.

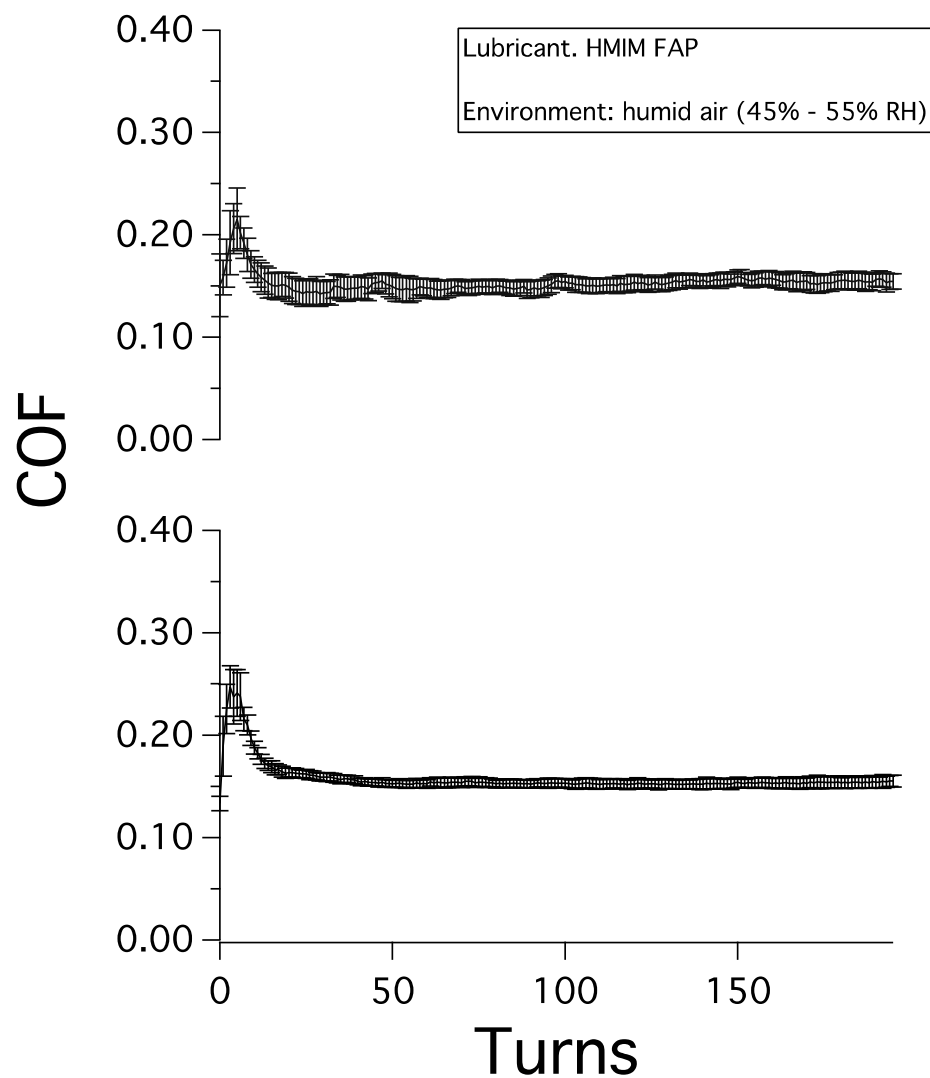


Figure S3: Coefficient of friction versus number of cycles (sliding time) during two tribological tests (normal load: 0.5 N sliding speed: 50 mm/min, radius: 3.2 mm) carried out in the presence of [HMIM] FAP at room temperature (296 ± 2 K) and humid air (45% - 55% RH). Error bars express the standard deviation of friction data over a single cycle.

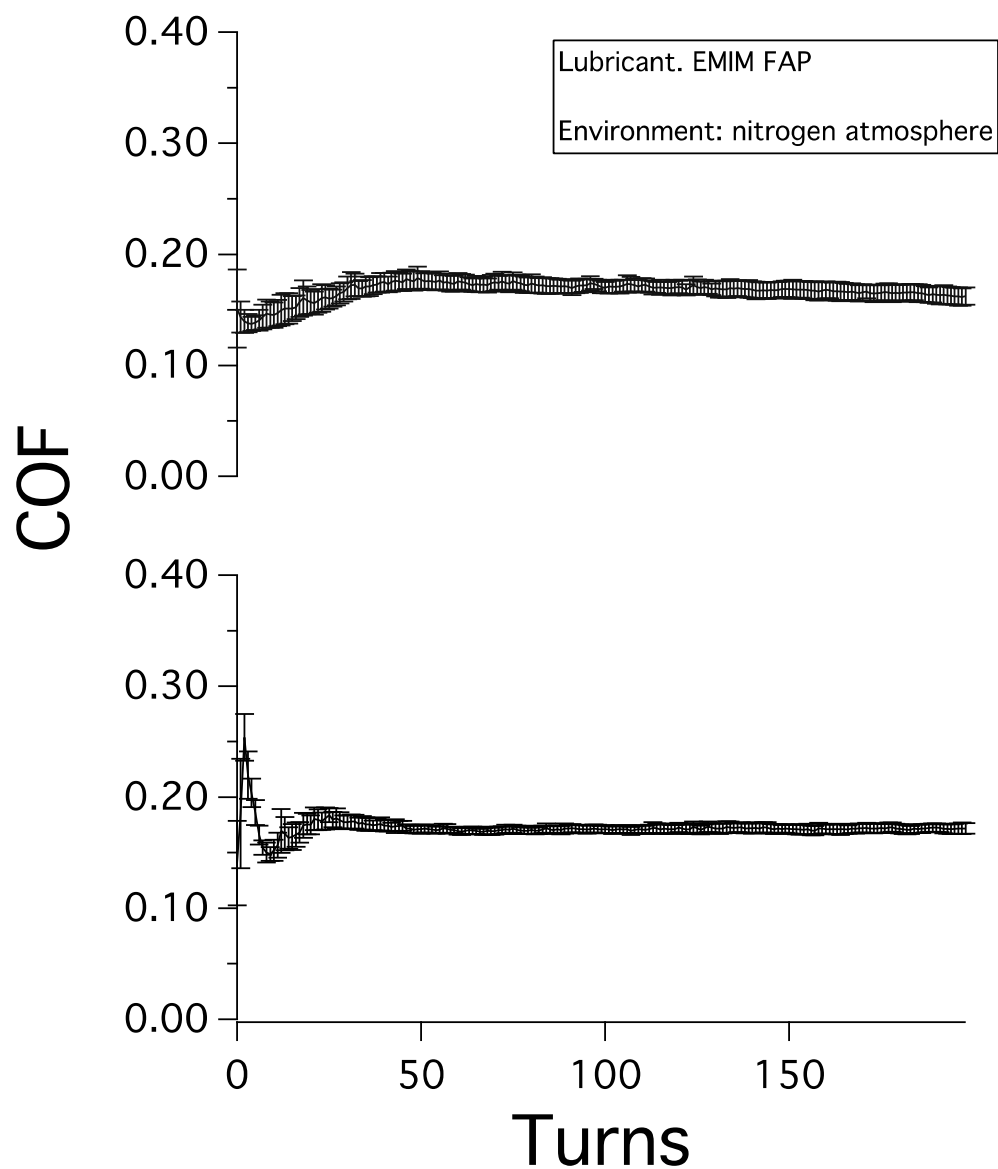


Figure S4: Coefficient of friction versus number of cycles (sliding time) during two tribological tests (normal load: 0.5 N sliding speed: 50 mm/min, radius: 3.2 mm) carried out in the presence of [EMIM] FAP at room temperature (296 ± 2 K) and under nitrogen. Error bars express the standard deviation of friction data over a single cycle.

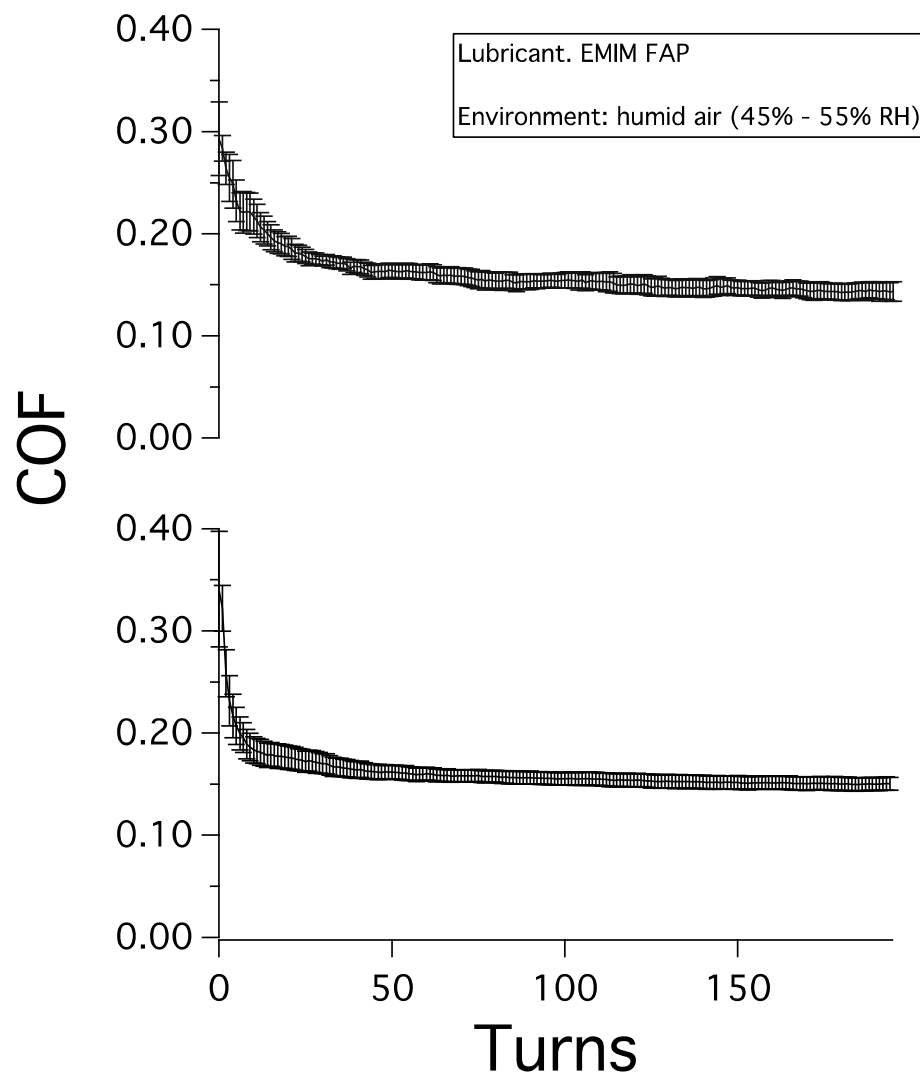


Figure S5: Coefficient of friction versus number of cycles (sliding time) during two tribological tests (normal load: 0.5 N sliding speed: 50 mm/min, radius: 3.2 mm) carried out in the presence of [EMIM] FAP at room temperature (296 ± 2 K) and humid air (45% - 55% RH). Error bars express the standard deviation of friction data over a single cycle.

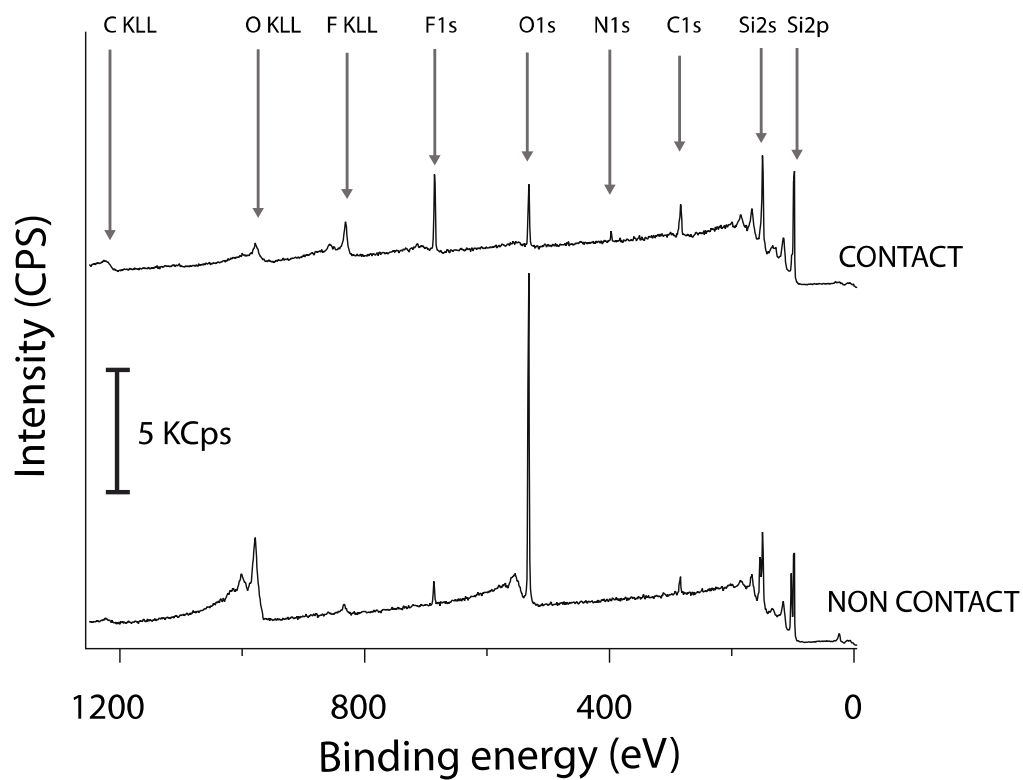


Figure S6: Survey XP-spectra of a silicon disk lubricated with [EMIM] FAP under a nitrogen atmosphere. Normal load: 4.5 N, sliding speed: 50 mm/min, number of cycles: 200, radius: 3.2 mm.

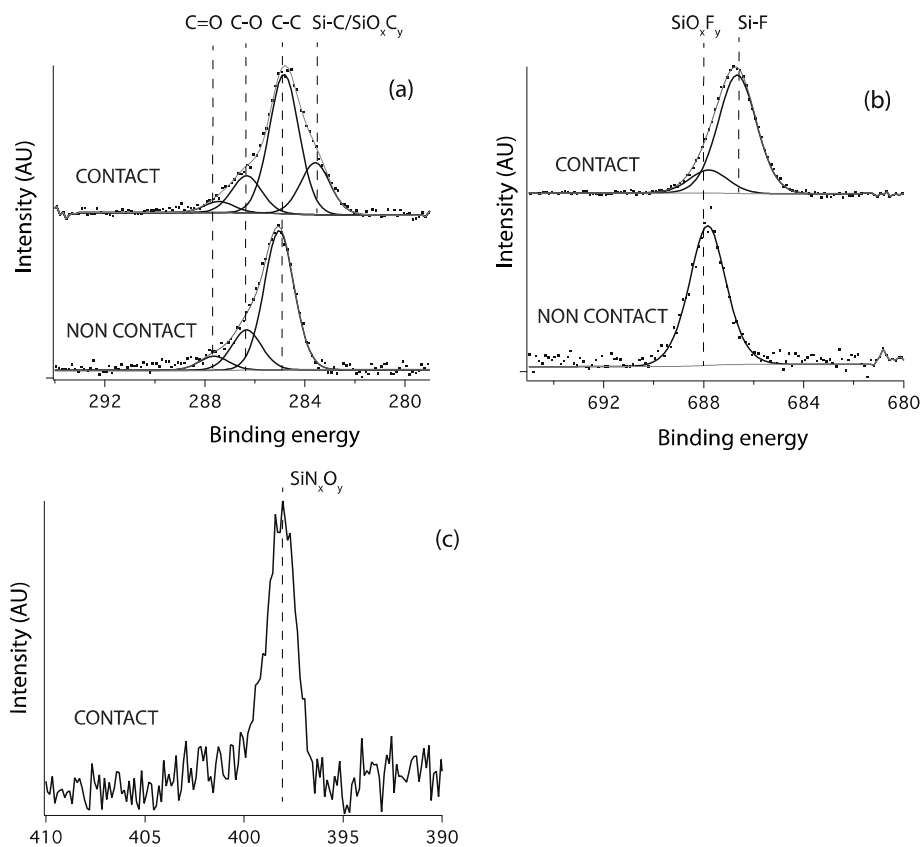


Figure S7: C1s (a), F1s (b) and N1s (c) regions of the XP- spectra of a silicon disk lubricated with [EMIM] FAP in the presence of a nitrogen atmosphere. Normal load: 4.5 N, sliding speed: 50 mm/min, number of cycles: 200, radius: 3.2 mm.

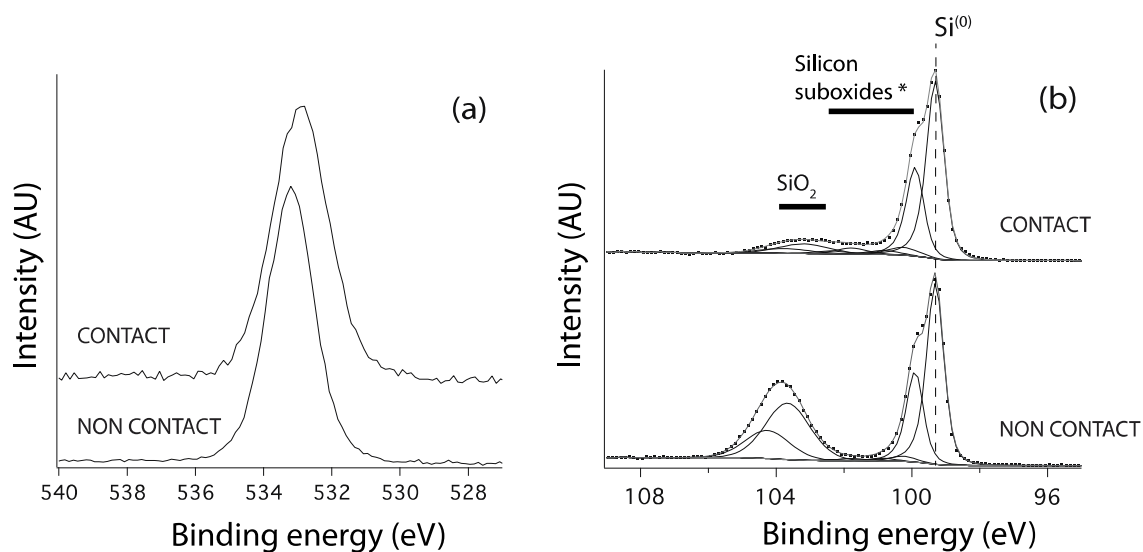


Figure S8: O1s (a) and Si2p (b) XP-spectra of a silicon disk lubricated with [EMIM] FAP in the presence of a nitrogen atmosphere. Each Si signal is fitted with two components due to spin-orbit coupling ($2p_{3/2}$ and $2p_{1/2}$). The region labeled as “Silicon suboxides” could also contain contributions from SiO_xF_y , SiC_xO_y , SiN_xO_y . Normal load: 4.5 N sliding speed: 50 mm/min, Normal load: 4.5 N, sliding speed: 50 mm/min, number of cycles: 200, radius: 3.2 mm.

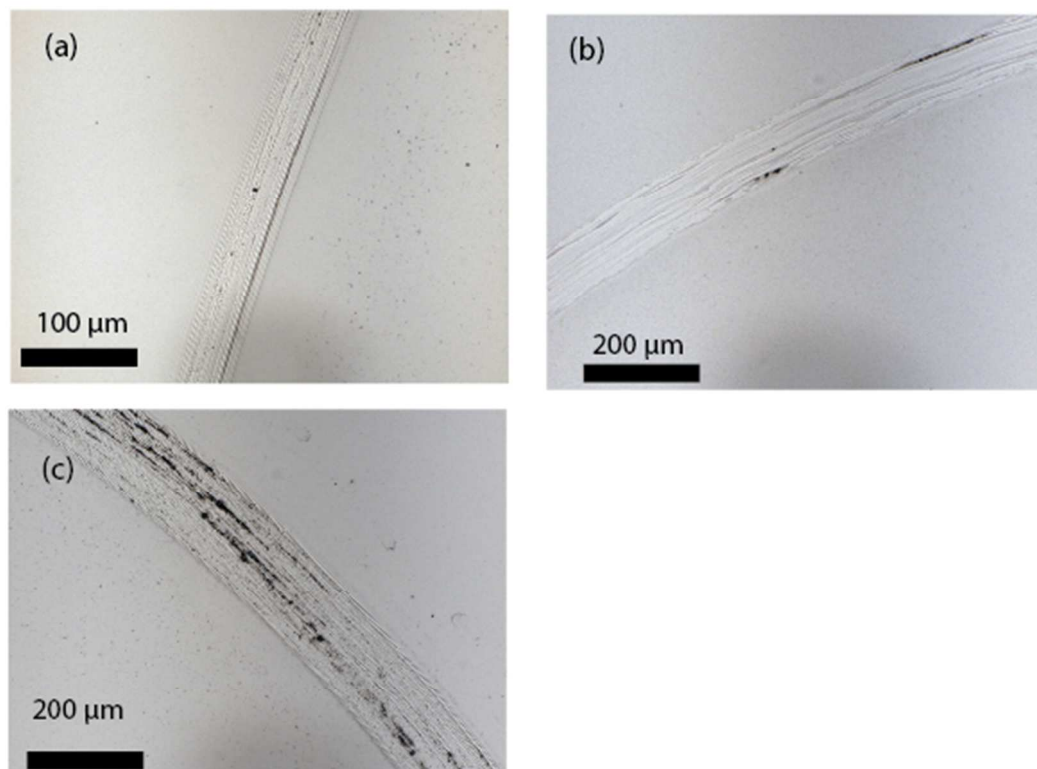


Figure S9: Optical micrographs of the contact area of silicon wafers lubricated with [EMIM] FAP; (a) normal load: 0.5 N, environment: humid air (45%-55% RH); (b) normal load: 4.5 N, environment: nitrogen atmosphere; (c) normal load: 4.5 N, environment: humid air (45%-55% RH). All the tests were performed at a sliding speed of 50 mm/min and a duration of 200 cycles (radius: 3.2 mm)

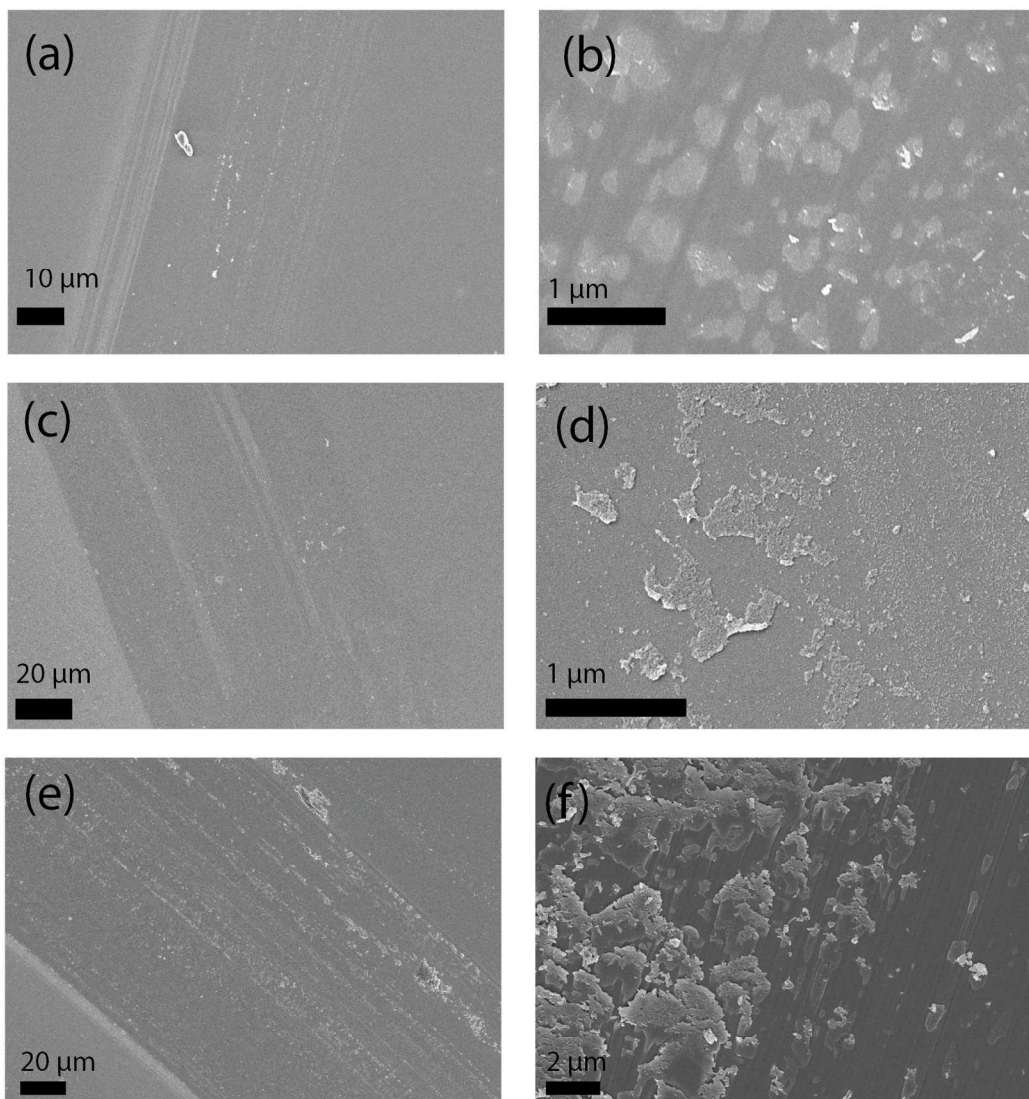


Figure S10: SEM images of the contact area of silicon wafers lubricated with [EMIM] FAP; (a) and (b) normal load: 0.5 N, environment: humid air (45%-55% RH); (c) and (d) normal load: 4.5 N, environment: nitrogen atmosphere; (e) and (f) normal load: 4.5 N, environment: humid air (45%-55% RH). All the tests were performed at a sliding speed of 50 mm/min and for a duration of 200 cycles (radius: 3.2 mm).

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